

SETO CSP Program Summit 2019

# LOW-COST HIGH TEMPERATURE CERAMIC HEAT EXCHANGERS

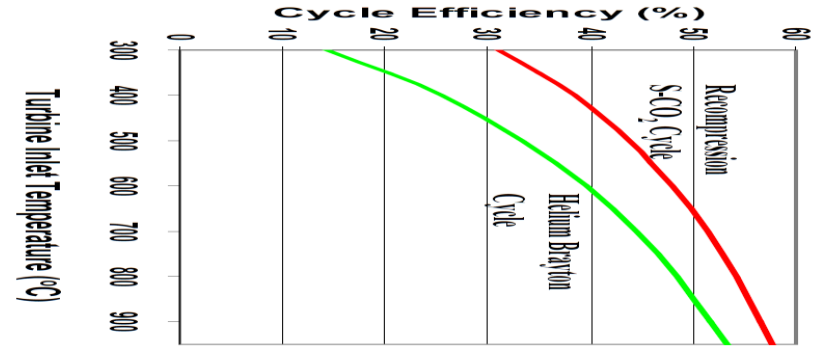
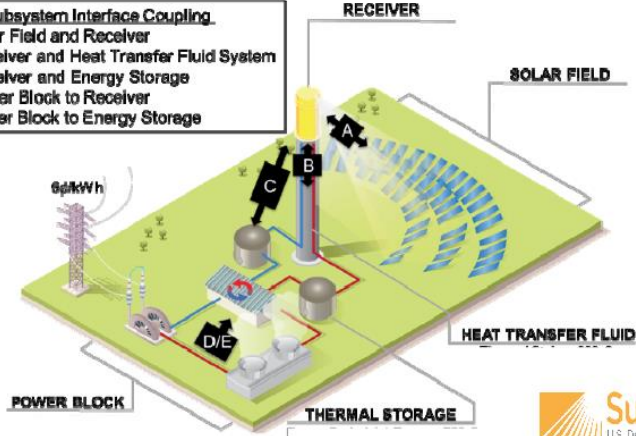
March 19, 2019

Oakland, CA

# Background

## CSP Subsystem Interface Coupling

- A: Solar Field and Receiver
- B: Receiver and Heat Transfer Fluid System
- C: Receiver and Energy Storage
- D: Power Block to Receiver
- E: Power Block to Energy Storage



V. Dostal

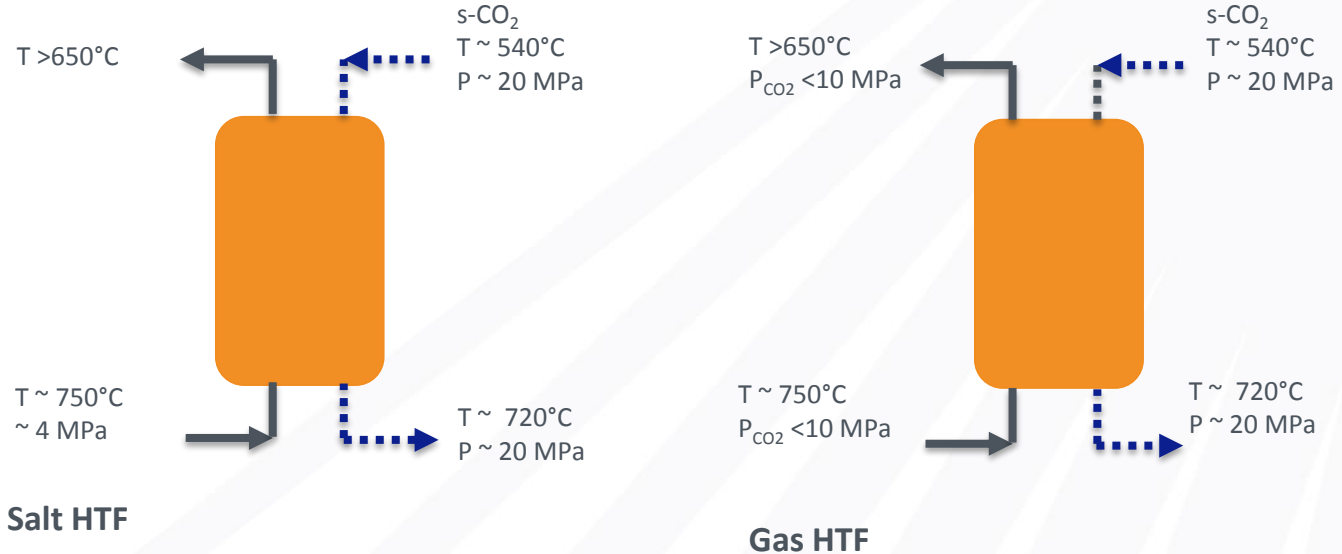
HXs for Thermal Energy Transfer from HTF to s-CO<sub>2</sub>

T > 700°C

P ~ 20 MPa for s-CO<sub>2</sub>

**Higher Temperatures (>700°C) and Pressures Require Components (HXs, TES, etc.) that Perform Reliably at the Operating Conditions**

# CSP – High Temperature Heat Exchangers



From: Gen3 RoadMap 2017

## Higher Operating Temperatures with Challenging HTFs

- Corrosion from salt based HTF
- Oxidation
- Creep

# Proposed concept – Why ceramics?

---

- High melting point, high temperature thermodynamic stability
- Compatible to variety of HTFs and working fluid
- High corrosion resistance (salts, s-CO<sub>2</sub>)
- High oxidation and fouling resistances
- Good thermal conductivity at elevated temperatures
- High creep resistance at operating temperatures
- Inexpensive raw materials

Traditional ceramic processing and machining processes are difficult and expensive

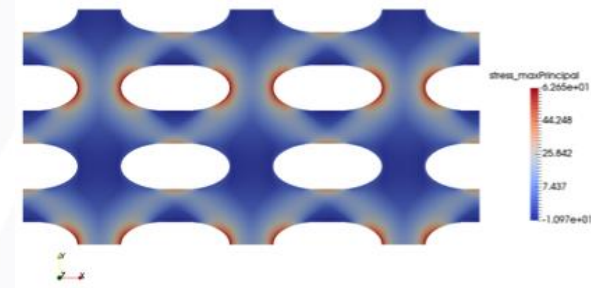
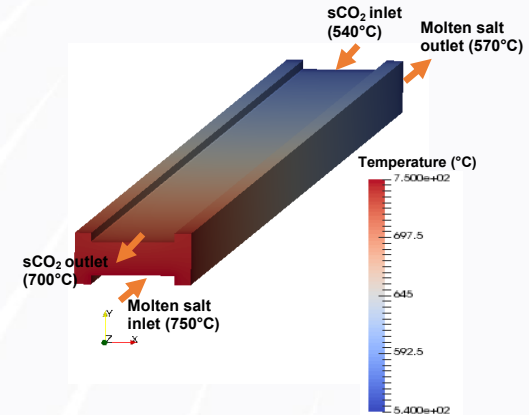
# Proposed concept – Additive manufacturing

---

- **Ease of Fabrication and Manufacturing**
  - Complex geometries (shapes with curvatures and sharp transitions can be fabricated)
- **Tailorable Composition and Properties**
  - composites can be fabricated by manipulating the preform compositions
- **Lower cost**
  - Reduced processing steps
  - Shorter production times
  - Design changes can be easily incorporated in manufacturing

# Key Tasks

- HX design using combined CFD & thermal/stress modeling
- Fabrication and characterization of HX plates
- Fabrication of multilayered HX of optimized design
- Joining and durability evaluations
- Experimental testing and validate simulations
- Techno-economic analysis



Maximum principal stress profiles

# Challenges and mitigation plans

---

**Adequate pressure drops and stresses, while maintaining necessary thermal transport**

- CFD and conjugate thermal/stress analysis will dictate optimum HX design

**Densification**

- Temperature, heating/cooling rates

**Mechanical properties (toughness) and thermal shock resistance of ceramics**

- improve toughness and reliability and benefit thermal conductivity

**Integration of various HX components, ceramic/metal joining**

- match the thermal expansions between ceramic and metal

# Key Outcomes and Impact

---

- An advanced low-cost, corrosion and creep resistant thermal exchange system operating at temperatures  $>700^{\circ}\text{C}$  and compatible to salt and gas phase HTFs and  $\text{s-CO}_2$
- Higher temperature power cycles will help SETO program to achieve its LCOE targets
- Demonstrated performance (and associated data) for a reliable ceramic HX at lab-scale
- Innovations in materials and manufacturing will benefit not only CSP, but other power generation and process industries